

Project Monitor Form

Project: CMS FED Date: Friday 14 Jan-2005	PMF number: 52 Sheet: 1 of 2
<p>Project Implementation phase.</p> <p>FEDv2</p> <p><i>Manufacture of Pre-series</i> Production of 5 + 20 off FEDv2:</p> <p>Assembly of first 5 boards commenced week of Dec 13th as anticipated. However, there were problems discovered with the metal finish of the pcbs (gold not attaching to a number of pads). It was found that even after repair at DDi Tewksbury the boards were not acceptable for assembly. Therefore pcbs from the 2nd batch of 20, which are ok have been used instead. DDi will manufacture more pcbs to make up the difference, but this should not affect the overall schedule. There was one board which had the bottom side assembled before the metallisation problem was discovered. As we couldn't be fully confident that the top side is safe for BGA assembly it was decided not to attempt the top side assembly.</p> <p>Otherwise the assembly went smoothly with only minor queries. We expect 5 boards to be delivered on Friday 14th Jan. Allowing 2 weeks for commissioning, the assembly of the remaining 20 boards will now commence week starting Mon 31st Dec. Assembled boards will be delivered in 4 batches of 5 commencing week of Mon Feb 21st.</p> <p><i>Design Testing :</i></p> <p>Tests on S-LINK readout on FEDv2 are continuing. The BE FPGA timing has been adjusted and no S-LINK errors have been observed during high rate/occupancy runs of over 10^9 events. VME readout may also need some adjusting, although tests of up to 10^7 events have reported no errors.</p> <p>A preliminary report detailing the results of FE Analogue tests by Stefanos Dris at CERN of FEDv1 concluded that the load resistor should be lowered to 62 Ohm, but there is no improvement in settling time in changing the ADC input capacitor value from 4.7 pF. Results need to be confirmed on a FEDv2.</p> <p><i>Firmware :</i></p> <p>TTC chan B commands : Resync has been implemented (needs testing).</p> <p>Two new Tracker header formats have been introduced :</p> <ul style="list-style-type: none"> i) "Full Debug mode" with existing full status information from APVs and FE lengths plus an extra word containing mode and diagnostic information ii) "APV Error mode" with condensed status information* on APV status and without FE lengths. <p>See latest BE FPGA technical description for full details at http://www.te.rl.ac.uk/esdg/cms-fed/firmware/Documents/BE_FPGA_Technical_Description.doc</p>	

*The full debug information is also provided in VME registers for monitoring (needs testing).

Sufficient information is provided to enable the readout software to recognise header and reconstruct event information. Readout software will need updating to handle mode ii).

Assembly Plant Testing

The manufacture test plan procedures have been optimised and this is also implemented in the LabView application.

DDi test section chief Peter Stoneham visited RAL on 30 Nov to inspect our existing test set-up and procedures. They were very satisfied with the arrangements and do not envisage any difficulties in carrying out our proposals for test. It was decided that we would provide DDi with all the equipment (including Boundary Scan kit) needed for the Assembly plant testing. This was followed up with a visit to DDi on 6th Jan to inspect the assembly plant and test facilities and for further discussions with Peter Stoneham.

JTAG representative James Stanbridge visited RAL 7th Dec and demonstrated improved Boundary Scan tools.

Other Items

Ivan modified (e.g. 62 Ohm resistors) 5 existing FEDv1 boards at CERN (nrs 005, 013, 014, 015, 016).

However, the proposed upgrade (by adding LVDS clock) to be compatible with latest FEDv2 firmware was not successful (due to bug in Firmware which is now corrected).

Nb |CFlash cards were then inadvertently reloaded with slightly out of date v1 firmware, but this should not affect LSA testing.

Recommended FEDv1 firmware is still:

ACE File: 16_07_04_1500 = (Delay 02_1B ; FE 03_16 ; BE 02_43)

EPROM : VME_03_0F

Two boards still report problems. Plan to send back to RAL for investigation.

Nr 17 at RAL is being modified and re-tested as a replacement.

The spreadsheet detailing the location and status of all FED boards has been updated on the web.

Final FED crate order has been submitted with clarification of crate specs after discussions with Paul Harwood at CERN ESS.

James and Greg successfully installed full 4 x FED Tester system at RAL with a FED Kit and the latest test software. Full speed readout tests are now being carried out at RAL.

Lab area at RAL has being rearranged in preparation for arrival of the rack from CERN.

Some kit needed for full crate tests is missing (e.g. second LHC crate, suitable crate controller).

To be discussed at this meeting.

Final Production:

Updated quote from DDi, which adds assembly testing and front panel manufacture costs, has been received.

Our submission to the CERN Finance Committee in March has been correspondingly revised.

A full stock check of components remaining at RAL after pre-series production is in progress. Components on long lead times are being identified in collaboration with DDi with a view to RAL purchasing sufficient quantities to avoid delays in starting the first batch of the final production (DDi can't commence procurement until a contract is agreed).

A follow up meeting with DDi to discuss contract issues is proposed for end of Feb.

Actions from the previous PMF			
Action	Status	Who	Original Target date
Implement Firmware for TTC chan B commands	Resync implemented	ST	06-12-04
Implement reduced Tracker header format.	Done	ST	06-12-04
Implement error monitoring spy channel.	Done	ST	06-12-04

Actions outstanding and new actions		
Action	Who	Target Date
Commission first 5 boards using LabView App	IC	21-01-05
Test first 5 boards using SLINK & VME readout	ST	28-01-05
Mod nr 17 and 19 and send to CERN	IC	28-01-05
Test new Tracker header format contents	JC	31-01-05
Test new monitoring spy channel	JC	31-01-05
List kit needed for full crate tests	JC	17-01-05
Coordinate pre-series production with DDi	JC	07-03-05
Order chiller unit	IC	31-01-05
Update Finance Ctte submission doc	JC	17-01-05
Stock check and spreadsheet of remaining FED components	IC	11-02-05
Implement comments and release new BE FPGA technical doc	ST	31-01-05

Project Monitor Form- milestones

Project: CMS FED		PMF number: 52		
Project Manager: J. Coughlan				
Date: Friday 14 Jan-2005		Sheet: 2 of 2		
	Milestones from Project Management Plan Version:1.6	date due in PMP	predicted date	date done
1	User Requirements Document	30.07.01		26.09.01
2	Project Spec sign off	21.12.01		05.02.02
3	Board Level Preliminary Review	14.01.02		16.01.02
4	FE Analogue Channel Feasibility Review	31.01.02		21.03.02
5	FE Module Feasibility Review	28.02.02		08.05.02
6	Board Level Feasibility Review	25.02.02		25.02.02
7	Delay FPGA Interim Review	11.03.02		27.03.02
8	Front End FPGA Interim Review	28.02.02		12.08.02
9	Back End FPGA Interim Review	04.03.02		17.12.02
10	FE Module Final Review	18.06.02		25.06.02
11	BE Module Interim Review	28.06.02		15.08.02
12	Schematics finalised	05.08.02		22.08.02
13	Layout & Routing done	16.09.02		29.10.02
14	Full Board FEDv1 Design Final Review	23.09.02		06.11.02
15	IDR Customer Production sign off & PCB Tape Out	07.10.02		06.12.02
16	Batch 1 (2 off) Non-Opto Assembled FEDv1s at RAL	11.11.02		22.01.03
17	Old version OptoRx for Batch 0 in UK	26.08.02		28.01.03
18	Batch 2 (3 off incl 1 Opto) Assembled boards at RAL	20.06.03		27.06.03
19	New version OptoRx at RAL	01.04.03		21.07.03
20	FEDv1 Interim Review	08.09.03		11.09.03
21	Batch 3 (6 off all opto) Assembled boards at RAL	30.09.03		08.10.03
22	Ship 1st FEDv1 to CERN.	30.09.03		03.11.03
23	Ship 2nd FEDv1 to CERN.	28.11.03		19.12.03
24	Batch 4 (6 off DDi) Assembled boards at RAL	01.03.04		22.03.04
25	Finalise design changes for FEDv2	01.04.04		25.03.04
26	Design Review FEDv2	18.06.04		04.06.04
27	FEDv2 tape-out	16.07.04		28.06.04
28	First FEDv2 boards at RAL	08.10.04		02.08.04
29	Dispatch calls for Tender	26.08.04		13.09.04
30	Award Tender contract	09.02.05		
31	FEDv3 tape-out	06.04.05		
32	First FEDv3 boards at RAL	13.07.05		
33	Production of 500 FEDv3 starts	08.09.05		
34	First FEDv3 at B904 Preveessin	30.11.05		
35	First FED installed at USC55	17.11.05		
36	Last FED installed at USC55	26.07.06		
37	Power on Tracker	01.08.06		
38	Readout test with Tracker	01.10.06		
39	LHC test run	02.04.07		